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(54) **Title:** ELECTRICAL CONNECTION INTERFACE FOR CONNECTING ELECTRICAL LEADS FOR HIGH SPEED DATA TRANSMISSION

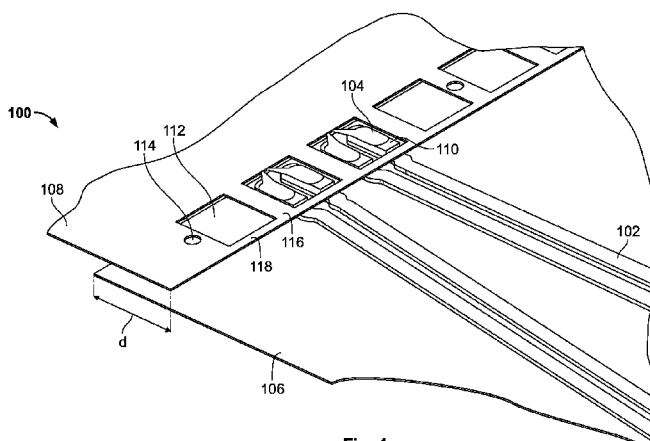


Fig. 1

(57) **Abstract:** The present invention relates to an electrical connection interface for connecting electrical leads for high speed data transmission, comprising a first substrate carrying at least one first electrically conductive lead (102, 102') having an interface region connected to at least one second electrically conductive lead (104, 104'), and at least one first ground plane layer (106, 106'). A second substrate carries the at least one second electrically conductive lead having an interface region connected to the at least one first electrically conductive lead, and at least one second ground plane layer (108, 108'). The electrically conductive leads are arranged on adjacent surfaces of the substrates. The ground plane layers (106, 106'; 108, 108') are electrically insulated from the respective conductive leads and are arranged to at least partly overlap each other.

